



Material Content Data Sheet



Sales Product Name		IPD082N10N3 G		Issued		25. September 2017		
MA#		MA000973702						
Package		PG-TO252-3-311		Weight*		316.05 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.609	1.46	1.46	14583	14583
leadframe	non noble metal	iron	7439-89-6	0.143	0.05		453	
	inorganic material	phosphorus	7723-14-0	0.043	0.01		136	
	non noble metal	copper	7440-50-8	143.098	45.26	45.32	452765	453354
wire	non noble metal	aluminium	7429-90-5	4.726	1.50	1.50	14953	14953
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.913	0.61		6052	
	plastics	brominated resin	-	2.050	0.65		6485	
	organic material	carbon black	1333-86-4	2.186	0.69		6917	
	plastics	epoxy resin	-	18.446	5.84		58363	
	inorganic material	silicondioxide	60676-86-0	112.041	35.45	43.24	354501	432318
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11834	11834
plating	non noble metal	nickel	7440-02-0	0.086	0.03		274	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.03	1	275
solder	noble metal	silver	7440-22-4	0.094	0.03		298	
	non noble metal	tin	7440-31-5	0.075	0.02		239	
	non noble metal	lead	7439-92-1	3.600	1.14	1.19	11389	11926
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		61	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	copper	7440-50-8	19.177	6.07	6.08	60678	60757
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com